



VMDSEMI

VUDE1P2R075PA

Datasheet



VMDSEMI

General Description

Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
-12V	7.5mΩ@-4.5V	-34A
	7.8mΩ@-3.7V	
	9.1mΩ@-2.5V	
	15mΩ@-1.8V	

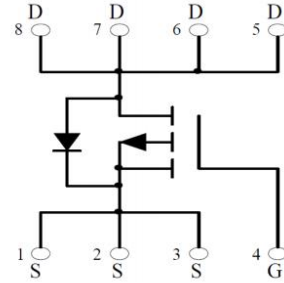


Figure 1 Symbol of VUDE1P2R075PA

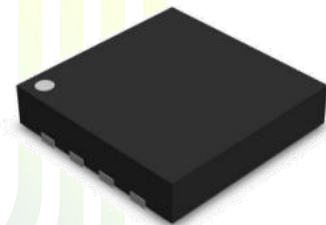
Features

- High cell density trench P-ch MOSFETs
- Super low gate charge
- Advanced high cell density Trench technology

Application

- Load Switch
- Battery protection applications

Package Type



DFN3X3-8L

Figure 2 Package Type of VUDE1P2R075PA

Ordering Information

Product Name	Package
VUDE1P2R075PA	DFN3X3-8L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-12	V
Gate-Source Voltage	V_{GSS}	± 10	V
Continuous Drain Current ^{Note1}	I_D	-34	A
Pulsed Drain Current ^{Note2}	I_{DM}	-102	
Total Power Dissipation ^{Note4}	P_D	3	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note5}	$R_{\theta JA}$		42		°C/W

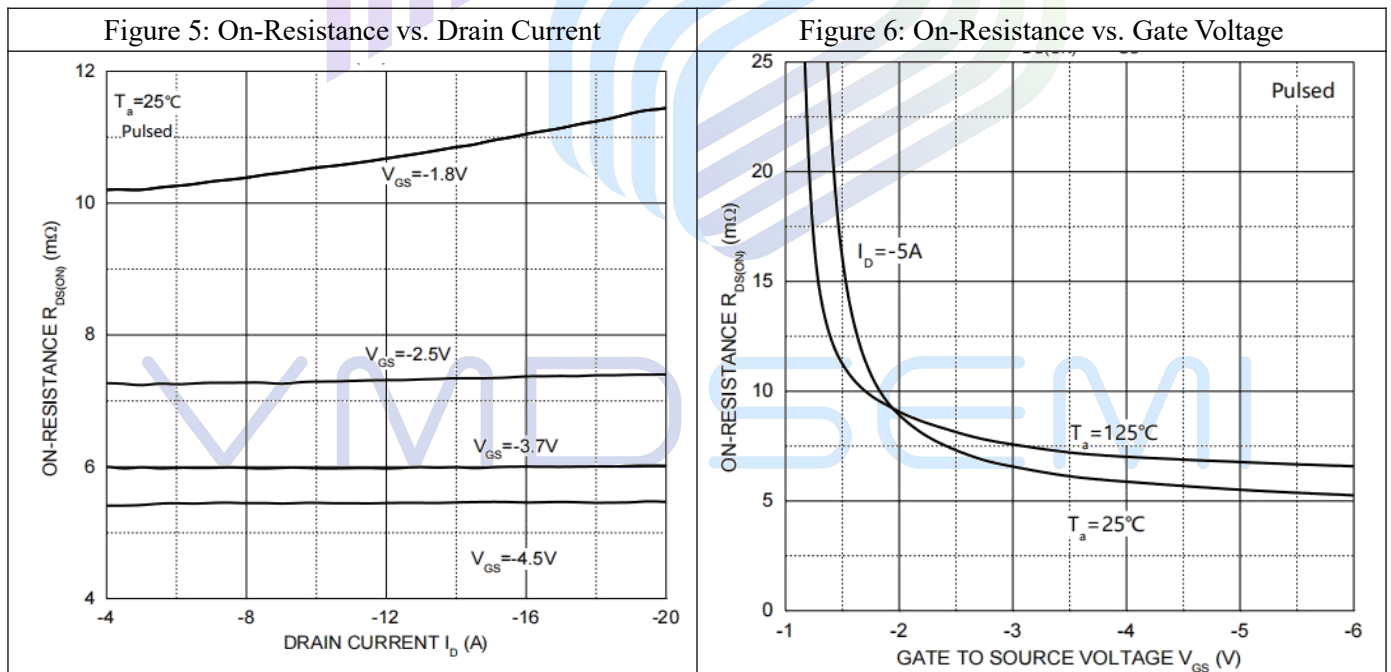
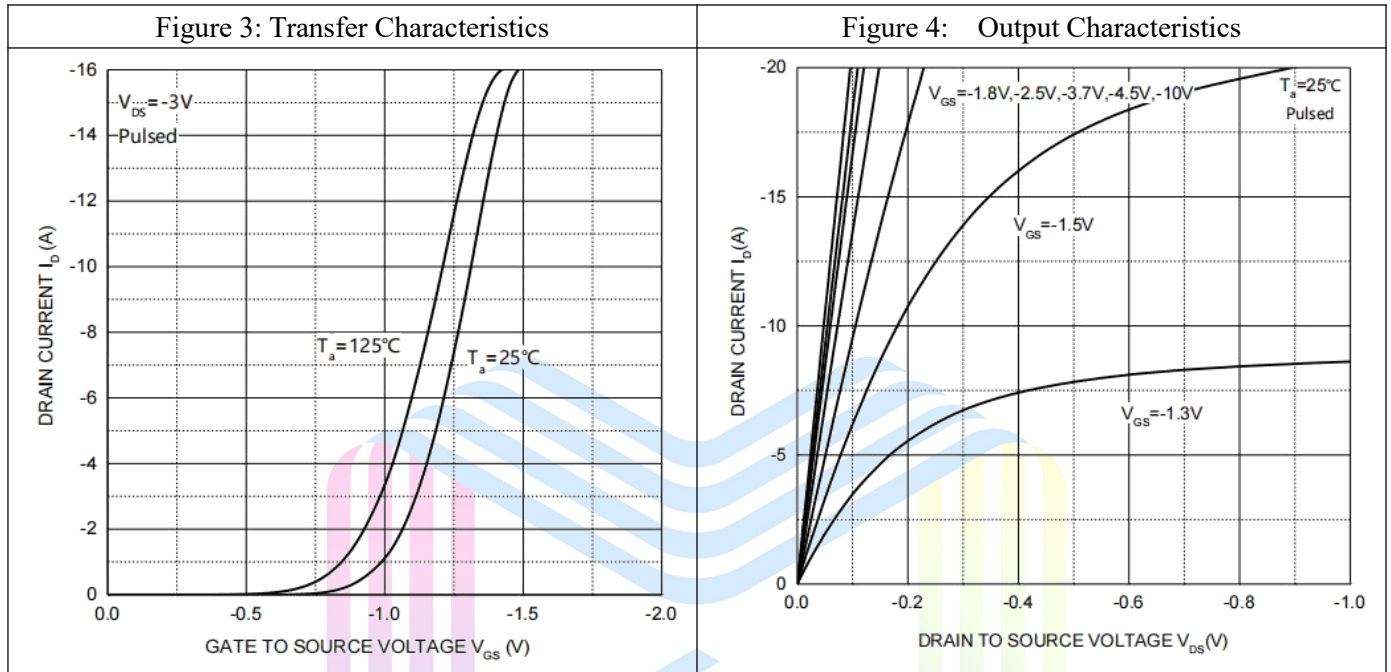


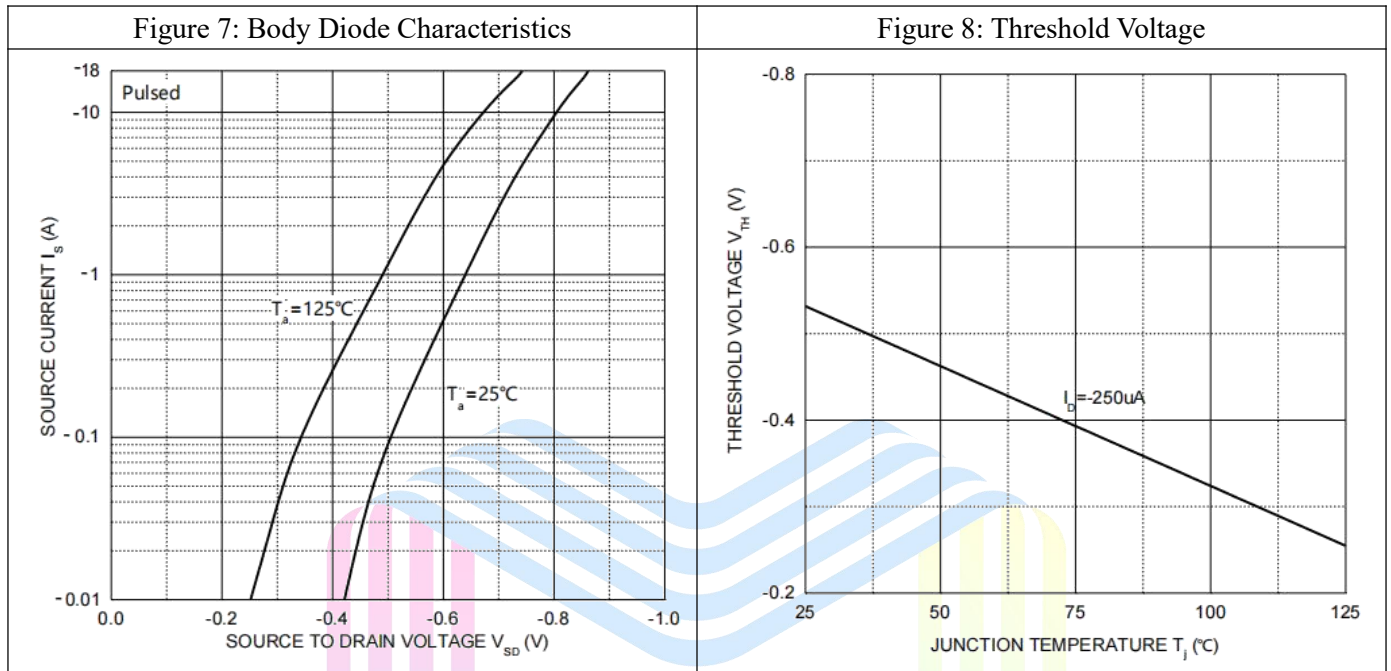
Electrical Characteristics ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	-12			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-12V, V_{GS}=0V$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note3}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.35	-0.5	-1	V
Static Drain-Source On-Resistance ^{Note3}	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-10A$		5.7	7.5	mΩ
		$V_{GS}=-3.7V, I_D=-10A$		6.0	7.8	
		$V_{GS}=-2.5V, I_D=-8A$		7.0	9.1	
		$V_{GS}=-1.8V, I_D=-6A$		10	15	
Forward Transconductance ^{Note3}	g_{FS}	$V_{DS}=-6V, I_D=-10A$	5			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=-6V$		4850		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		1520		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		1610		pF
Total Gate Charge	Q_g	$V_{DS}=-6V$		65		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=-4.5V$		20		
Gate-Drain Charge	Q_{gd}	$I_D=-5A$		325		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$			30	Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-6V$		22		ns
Turn-on Rise Time	t_r	$V_{GS}=-4.5V$		50		
Turn-off Delay Time	$t_{d(off)}$	$R_L=6\Omega$		100		
Turn-off Fall Time	t_f	$R_G=1\Omega, I_D=-4A$		30		
Diode Characteristics						
Diode Forward Voltage ^{Note3}	V_{DS}	$V_{GS}=0V, I_S=-10A$			-1.2	V
Continuous Source Current	I_S	$T_C=25\text{ }^\circ\text{C}$			-34	A
Pulsed Source Current	I_{SM}				-102	

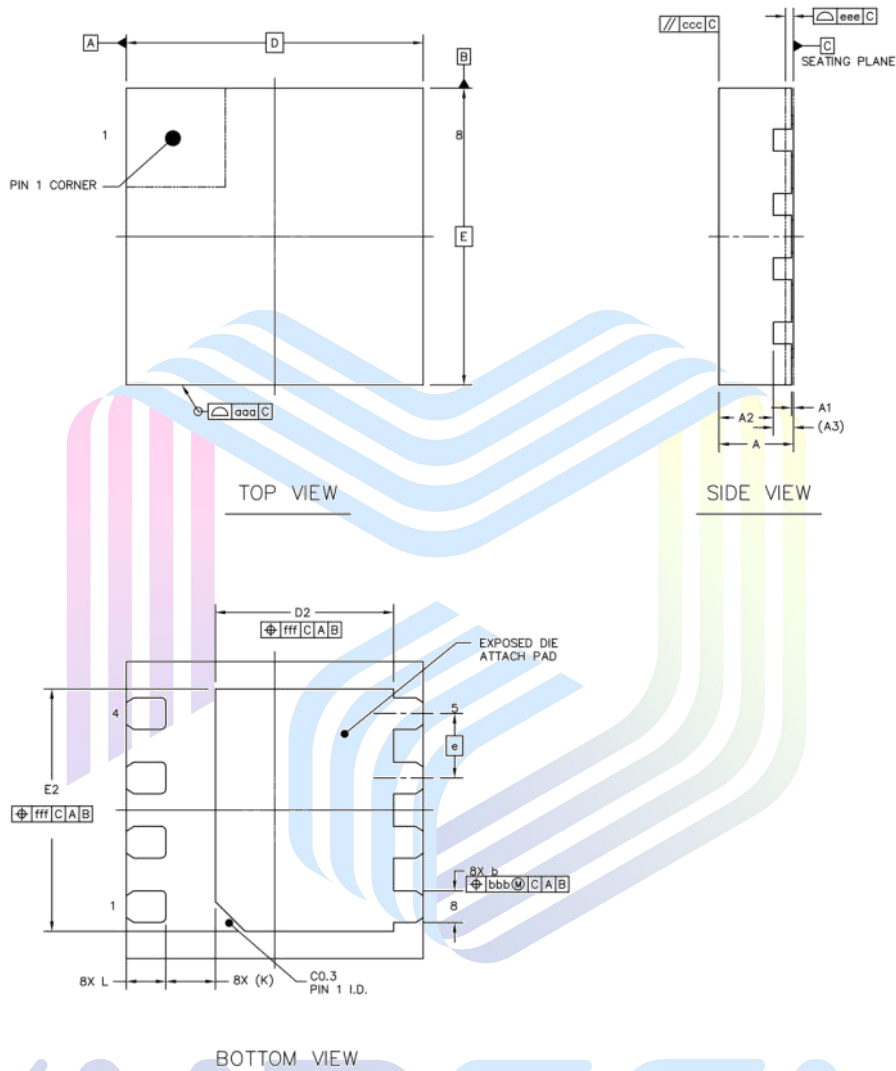
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 5.Device mounted on $1in^2$ FR-4 board with 2oz Copper, in a still air environment with $T_A = 25^\circ\text{C}$

Typical Performance Characteristics




VMDSEMI

Mechanical Dimensions:
DFN3X3-8L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.550TYP		0.022TYP	
A3	0.203REF		0.008REF	
b	0.270	0.370	0.011	0.015
D	3.000BSC		0.118BSC	
E	3.000BSC		0.118BSC	
e	0.650BSC		0.026BSC	
D2	1.700	1.900	0.067	0.075
E2	2.350	2.550	0.093	0.100
L	0.300	0.500	0.012	0.020
K	0.500REF		0.020REF	
aaa	0.100TYP		0.004TYP	
ccc	0.100TYP		0.004TYP	
eee	0.080TYP		0.003TYP	
bbb	0.100TYP		0.004TYP	
fff	0.100TYP		0.004TYP	

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